

HVM187S

Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0115-0400Z
(Previous: ADE-208-055C)
Rev.4.00
Oct.08.2003

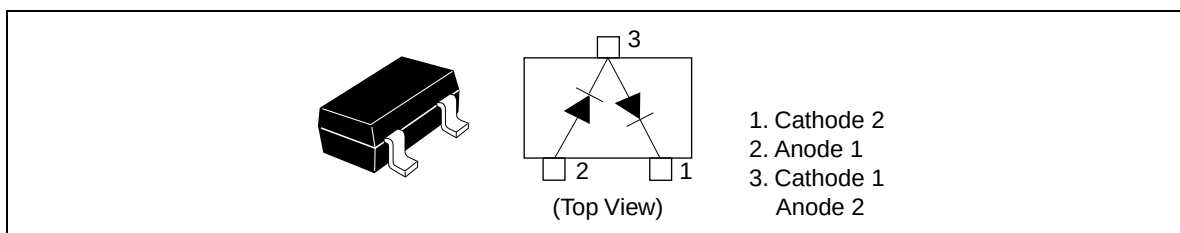
Features

- Low forward resistance. ($r_f = 5.5\Omega$ max)
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HVM187S	H3	MPAK

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	60	V
Forward current	I _F	50	mA
Power dissipation	Pd ^{*1}	100	mW
Junction temperature	T _J	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics ^{*1}

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I _R	—	—	100	nA	V _R = 60 V
Forward voltage	V _F	—	—	1.0	V	I _F = 10 mA
Capacitance	C	—	—	2.4	pF	V _R = 0 V, f = 1 MHz
Forward resistance	r _f	3.5	—	5.5	Ω	I _F = 10 mA, f = 100 MHz
ESD-Capability ^{*2}	—	200	—	—	V	C = 200 pF, Both forward and Reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; I_R ≥ 100 nA at V_R = 60 V

Main Characteristic

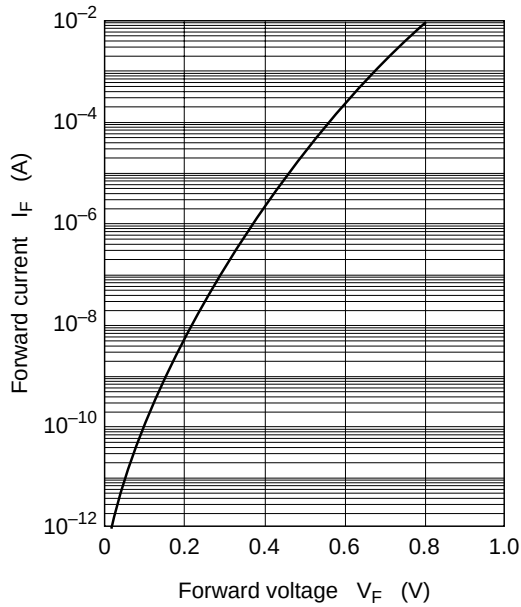


Fig.1 Forward current vs. Forward voltage

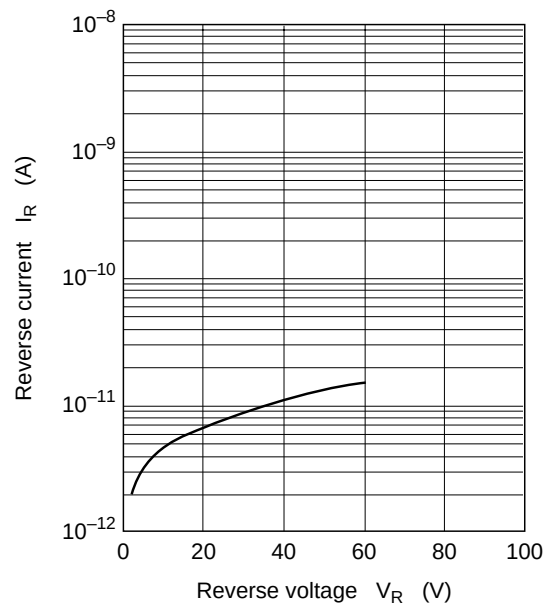


Fig.2 Reverse current vs. Reverse voltage

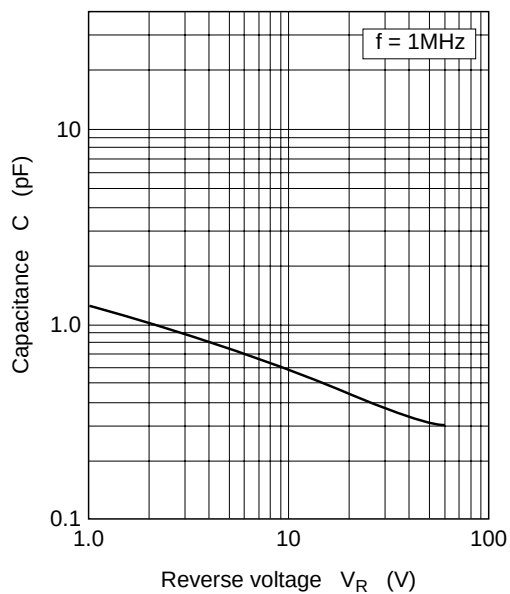


Fig.3 Capacitance vs. Reverse voltage

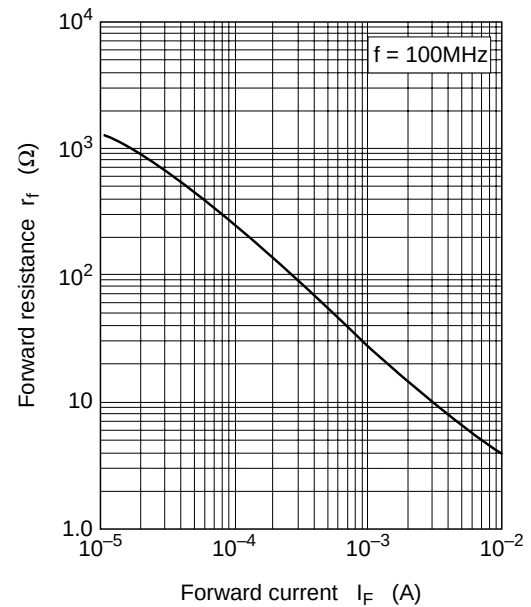
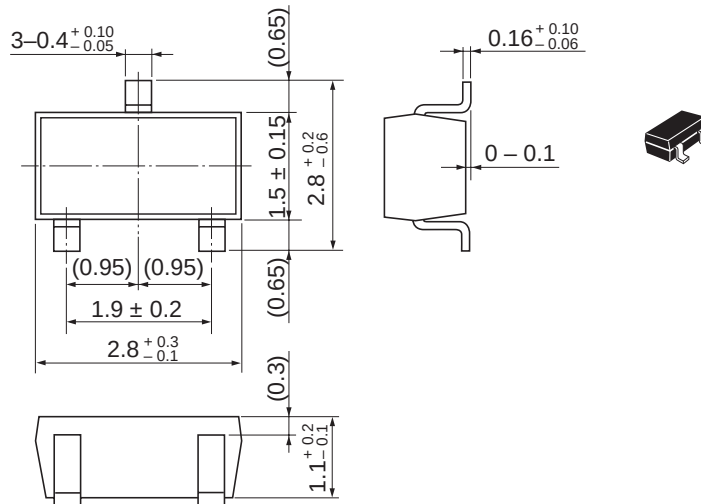


Fig.4 Forward resistance vs. Forward current

Package Dimensions

As of January, 2003

Unit: mm



Package Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom
Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

Renesas Technology Europe GmbH
Dornacher Str. 3, D-85622 Feldkirchen, Germany
Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

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26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001